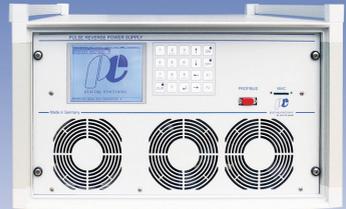


Wolfgang E. G. Hansal
Sudipta Roy

Pulse Plating

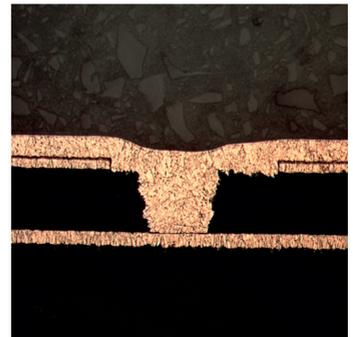
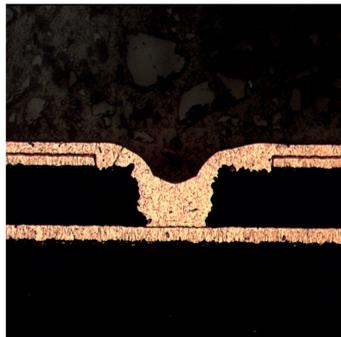
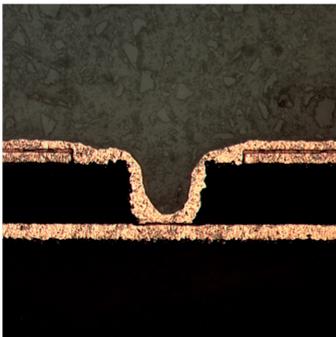


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